

液态感光阻焊油墨

(GH-8001G9A1)

GH-8001G9A1 为双组分网印 UV 接触曝光，稀碱显影的阻焊油墨，原有网印阻焊油墨无法达到的精密阻焊线路，高解像率的液态感光阻焊油墨可以解决。经高温硬化后的涂膜具有高绝缘性和高阻碍焊性，防水性等均不逊于 UV 硬化阻焊油墨。GH-8001 G9A1 特为化金及免洗阻焊剂而设计的特性，更适合使用于精密电路板。

| 技术特性 | |
|---------------|--|
| 颜色 | 绿 |
| 固体组份 | 75±2% |
| 粘度 (25℃) | 主剂: 180±40ps 固化剂: 70±20ps 主剂/固化剂: 0.75kg/0.25kg |
| 混合后粘度 | 180~200ps |
| 附着力 | 100/100 |
| 硬度 | ≥6H |
| 耐焊锡性 | 260±5℃ 10秒×2 无起泡, 无脱落 |
| 绝缘性 | 27KV/mm |
| 贮存期 (25℃) | 6个月 |
| 操作流程 | |
| 基板处理 | 酸处理→磨刷→水洗→烘烤→ 除尘 |
| 网目 | 36-57T |
| 预烤条件 75±2℃ | 第一面: 15-18分钟 第二面: 30-35分钟 |
| 曝光能量 | 21格底尺, 9-11格 300-450mj/cm ² |
| 显影 | 0.8-1.2wt%Na CO ₃ , 30±2℃ 压力 1.5-2.0kg/cm ² 显影时间: 35-50秒 |
| 水洗 | 水洗 1.5-2.0kg/cm ² |
| 后硬化 | 150℃, 60分钟 |

Liquid Photoimageable Solder Mask

(GH-8001 G9A1)

GH-8001 G9A1 series is a screen printable two-part liquid photoimageable solder mask and can be UV contact exposed then developed by dilute alkali. With high distinguish rate, it can be used in making high density solder-resist circuit boards, but the ordinary screen-printing solder-resist ink is unsolvable. After being high temperature curing, the film has high insulation and heat resistance, and its water resistance is better than the ordinary screen-printing solder-resist ink. GH-8001 G9A1 is specially designed for plating Aurum and using keep soldering flux, so it is better fit to be used in making high density circuit boards.

| Technique features | |
|--------------------------------|--|
| Color | GREEN |
| Solid content | 75±2% |
| Viscosity(25℃) | Base: 180±40ps Hardener: 70±20ps Base/ Hardener: 0.75kg/0.25kg |
| Viscosity after mixing | 180~200ps |
| Adhesion | 100/100 |
| Hardness | ≥6H |
| Resistance to Molten solder | 260±5℃ 10sec, 2times OK |
| Electric insulation Resistance | 27KV/mm |
| Shelf life (25℃) | 6months |
| Working procedure | |
| Surface treatment | Acid-treatment→blushing→ washing→stoving→dedust |
| Screen mesh | 36-57T |
| Pre-drying 75±2℃ | First side: 15-18min Second side: 30-35min |
| Exposure energy | Stuffer 21step, 9-11step 300-450 mj/cm ² |
| Developing | 0.8-1.2wt%Na CO ₃ , 30±2℃ Spraying pressure: 1.5-2.0kg/cm ² Time: 35-50sec |
| Clear | Water pressure: 1.5-2.0 kg/cm ² |
| After solidify | 150℃, 60min |

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一. Directions for use:

- (1) Mixing: According to the ratio of 3 parts base and 1 part
- (2) Hold time: 10-15min
- (3) Printing: 36-43T(90-110mesh)
Remarks: 1 μ m Ni/Au need to use 43T
- (4) Hold time: 10-15min
- (5) Pre baking: A(Printing and pre-baking first side, then printing and pre-baking second side); First side: 72-76°C*15-18min, Second side: 72-76°C*30-35min
B(Printing both sides together, then pre-baking both sides together): 72-76°C*30-35min
Remarks: The method B is recommended
- (6) Exposure: Stuffer step 9-12
- (7) Developing: Standard conditions:
 1. Developing solution: 0.8-1.2wt% aqueous Na CO solution
 2. Solution temperature: 28-32°C
 3. Spray pressure: 1.5-2.0kg/cm²
 4. Developing times: 35-50 seconds
 5. Water rinse duration: about 60 seconds
- (8) Post cure:
 1. HAL: 150°C × 60min
 2. 1 μ m Ni/Au, 1 μ m Sn: 150°C × 50 min